TEMPERATURE CONTROLLED SOLDERING IRON DEVICE WITH TEMPERATURE DISPLAY

A Project Study

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TABLE OF CONTENTS

TITLE PA	GE	
APPROV	AL SHEET	i
ACKNOW	/LEDGEMENT	ii
TABLE O	F CONTENTS	iii
LIST OF	ГABLES	V
LIST OF F	FIGURES	vi
ABSTRAC	CT	Vi
CHAPTER	R I: THE PROBLEM AND ITS BACKGROUND	
	Introduction	1
	Background of the Study	2
	Conceptual Framework	
	Statement of the ProblemSignificance of the Study	5
	Significance of the Study	6
	Scope and Delimitations	7
	Definition of Terms	8
CHAPTER	R II: REVIEW OF RELATED LITERATURE AND STUDIES	
	Conceptual Literature	9
	Related Studies	14
	Synthesis	19
CHAPTE	R III: RESEARCH METHODOLOGY AND PROCEDURE	
	Research Methods	20
	Data Gathering Procedure	20
	Construction Procedure	21
	Components used	23
	Testing and Evaluation	24

	Presentation of Data	26
	Analysis and Interpretation of Data	30
	Source Code Development	31
	Results of Testing and Evaluation	32
CHAPTE	ER V: SUMMARY, CONCLUSION AND RECOMMEND	ATION
	Summary	39
	Conclusion	40
	Recommendation	40
REFERE	INCES	
APPEND	DICES	

LIST OF TABLES

Table 4.1	Gross Leakage Test Data	32
Table 4.2	Thermocouple Amplifier Output Voltage Data	33
Table 4.3	Voltage Across Thermocouple Wires Data	33
Table 4.4	Melting Point Test Data Using the Proposed Device	34
Table 4.5	Melting Point Test Data Using	
	the Commercialized Soldering Controller	34
Table 4.6	Proposed Device Vs. Commercialized Soldering Controller	
	Percentage Difference	35
Table 4.7	Total Effectiveness	35
Table 4.8.1	Efficiency Test Data (300°C- 290°C)	36
Table 4.8.2	Efficiency Test Data (100°C- 200°C)	36
Table 4.8.3	Total Efficiency	37
Table 4.9.1	Reliability Test Data at Maximum Temperature Setting	37
Table 4.9.2	Reliability Test Data at Minimum Temperature Setting	38

LIST OF FIGURES

Figure 1.1 Research Paradigm	4
Figure 2.1 Transformer Powered Soldering Iron Device	-10
Figure 2.2 Weller Digital Soldering Controller	15
Figure 3.1 Temperature Controlled Soldering Iron Process Flow Design	21
Figure 3.2 Temperature Controlled Soldering Iron Control System Model	-22
Figure 3.3 Schematic Diagram	28
Figure 3.4 PCB Layout	29
Figure 4.1 Program Flow Chart	30



ABSTRACT

Title TEMPERATURE CONTROLLED SOLDERING

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This paper presents the innovation of a soldering iron device called TEMPERATURE CONTROLLED SOLDERING IRON DEVICE WITH TEMPERATURE DISPLAY. This device allows the user to control the temperature of the soldering iron device based from his desired temperature setting. This paper shall cover the process of how it was developed, its features, its limitations and technical specifications. Moreover, it shall include a background on how it was conceptualized. However, it shall not include thorough explanations and derivations of formulas of the theories involve in the project. At the end of this paper, it aims to introduce to the readers an innovative, yet low-cost soldering controller device.